

Part Number: L-56BGD

Green

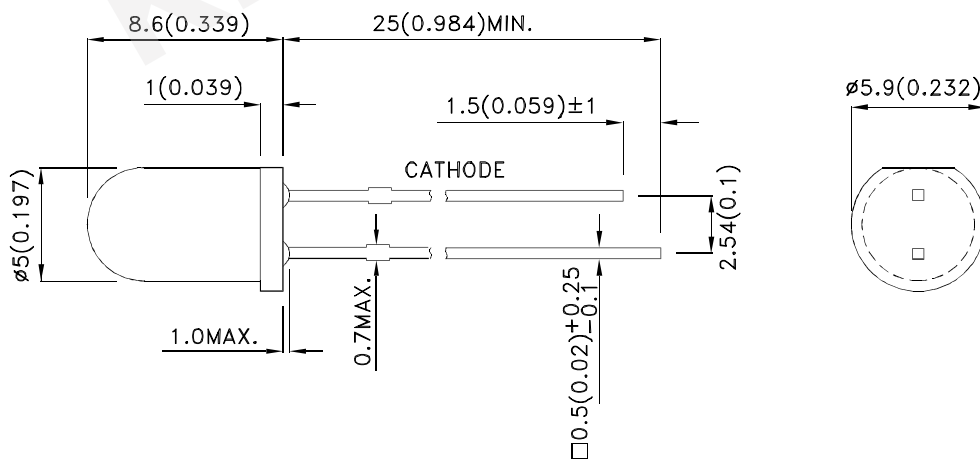
Features

- T-1 3/4 package.
- With built-in blinking IC.
- Operation voltage from 3.5V to 14V.
- Blinking frequency from 3.0Hz to 1.5Hz.
- RoHS compliant.

Description

The Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01)$ " unless otherwise noted.
3. Lead spacing is measured where the leads emerge from the package.
4. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.



Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) V= 9V		Viewing Angle [1]
			Min.	Typ.	2θ1/2
L-56BGD	Green (GaP)	Green Diffused	15	30	60°

Notes:

- θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
- Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Min.	Typ.	Max.	Units	Test Conditions
λ_{peak}	Peak Wavelength	Green		565		nm	
λ_D	Dominant Wavelength	Green		568		nm	
$\Delta\lambda_{1/2}$	Spectral Line Half-width	Green		30		nm	
I_F	Forward Current	Green	8	22		mA	Min:V _F =3.5V Typ:V _F =5V
I_{SON}	Supply Current	Green		8		mA	V _F =3.5V
I_{SON}	Supply Current	Green		44		mA	V _F =14V
f	Blink Frequency	Green	1.5		3	Hz	V _F =3.5V~14V

Note:

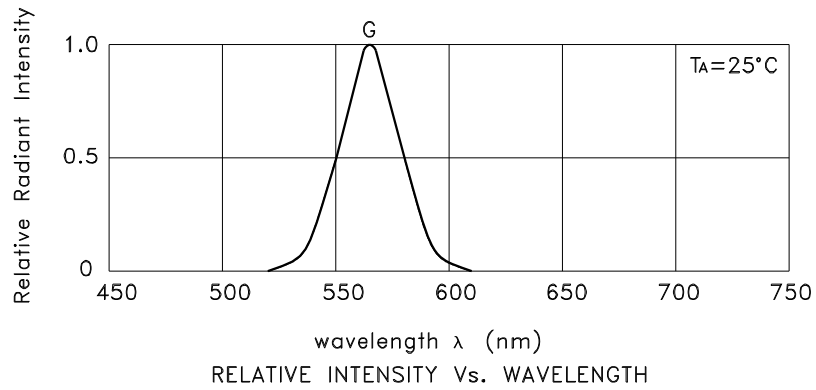
- Wavelength value is traceable to the CIE127-2007 compliant national standards.

Absolute Maximum Ratings at TA=25°C

Parameter	Green	Units
Power dissipation	310	mW
Forward Voltage	14	V
Reverse Voltage	0.5	V
Operating Temperature	-40°C To +70°C	
Storage Temperature	-40°C To +85°C	
Lead Solder Temperature [1]	260°C For 3 Seconds	
Lead Solder Temperature [2]	260°C For 5 Seconds	

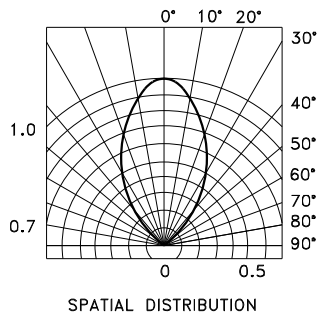
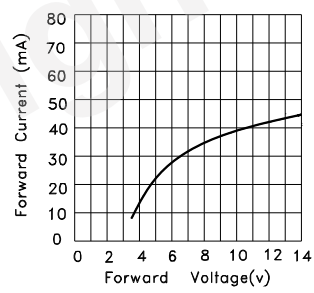
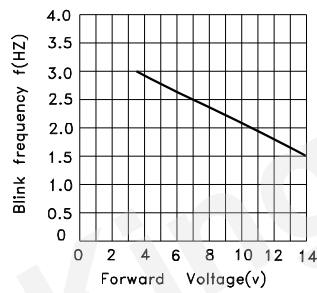
Notes:

- 2mm below package base.
- 5mm below package base.



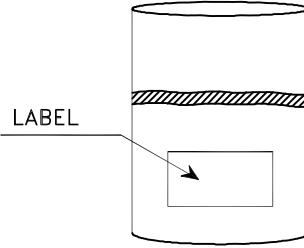
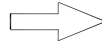
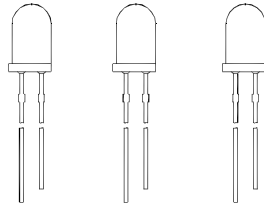
Green

L-56BGD



PACKING & LABEL SPECIFICATIONS

L-56BGD

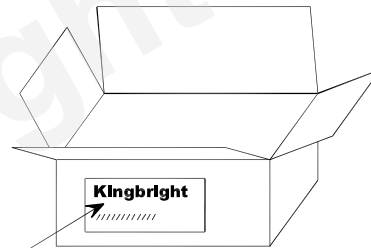


500PCS / BAG



32K / 9# BOX

OUTSIDE LABEL



OUTSIDE LABEL

16K / 5# BOX

<h2 style="margin: 0;">Kingbright</h2>					
P/NO: L-56Bxxx					
QTY: 500 pcs	Q.C.	<table border="1" style="margin: 0; width: 50px; height: 30px;"> <tr> <td style="text-align: center;">Q C</td> </tr> <tr> <td style="text-align: center;">xx xx xxxx</td> </tr> <tr> <td style="text-align: center;">PASSED</td> </tr> </table>	Q C	xx xx xxxx	PASSED
Q C					
xx xx xxxx					
PASSED					
S/N: XXXX					
CODE: XXX					
LOT NO:					
 xxxxxxxxxxxxxxxxxxxxxxxx					
RoHS Compliant					

PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures. (Fig. 1)

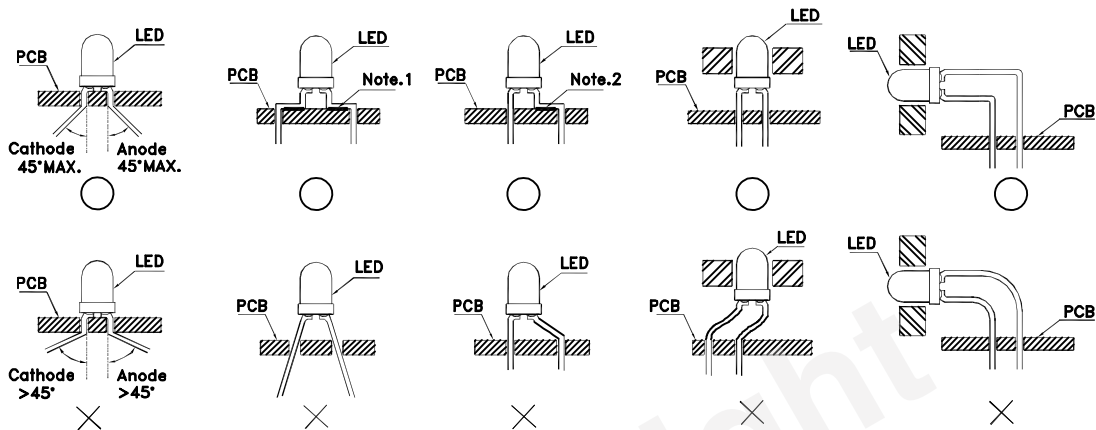


Fig.1

”O” Correct mounting method ”X” Incorrect mounting method

2. When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit. (Fig.2)
3. Use stand-offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.

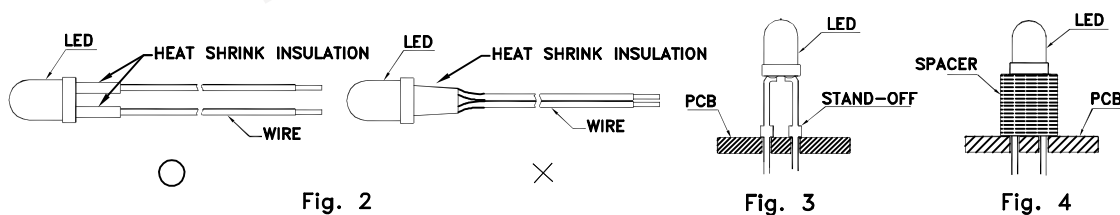


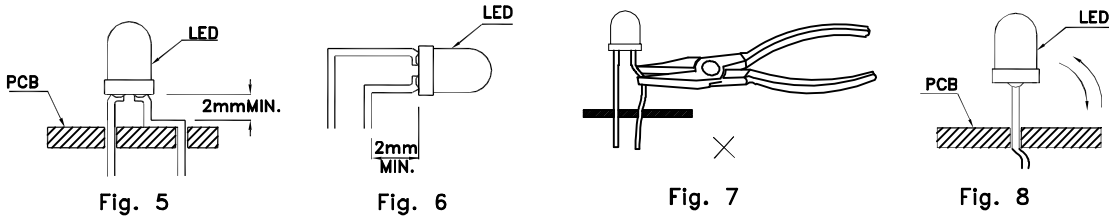
Fig. 2

Fig. 3

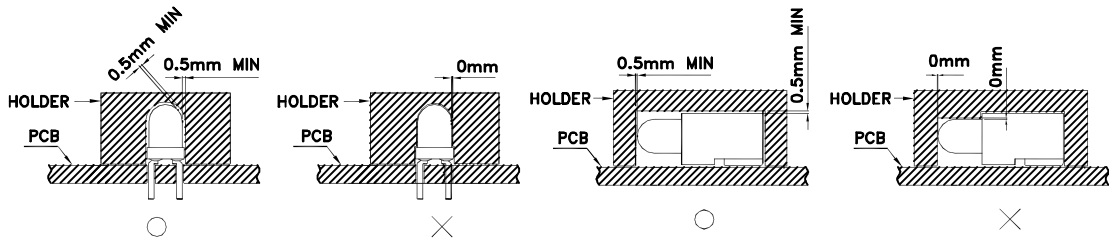
Fig. 4

4. Maintain a minimum of 2mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)
5. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)

6. Do not bend the leads more than twice. (Fig. 8)



7. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.

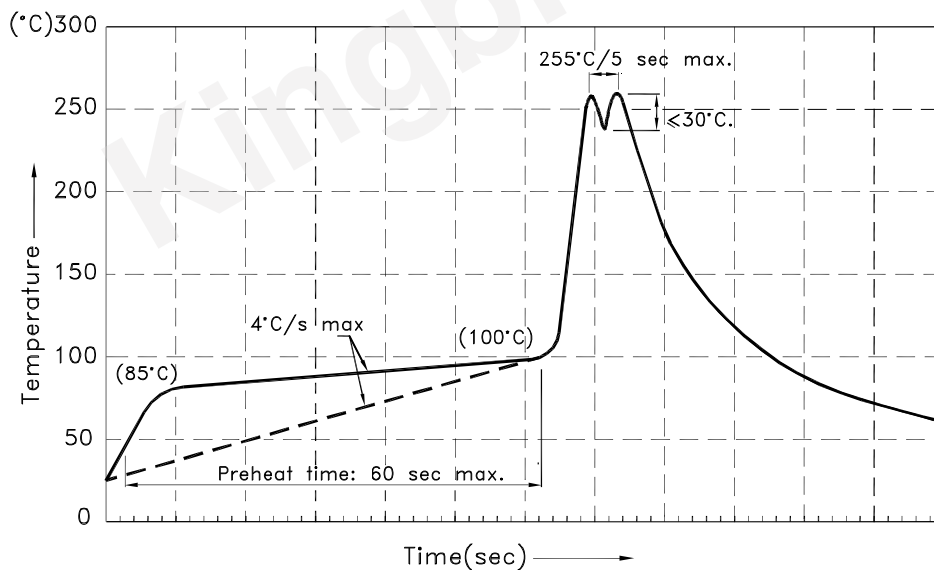


8. The tip of the soldering iron should never touch the lens epoxy.

9. Through-hole LEDs are incompatible with reflow soldering.

10. If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.

11. Recommended Wave Soldering Profiles:



Notes:

1. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
2. Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).
3. Do not apply stress to the epoxy resin while the temperature is above 85°C.
4. Fixtures should not incur stress on the component when mounting and during soldering process.
5. SAC 305 solder alloy is recommended.
6. No more than one wave soldering pass.

Detailed application notes are listed on our website.

http://www.kingbright.com/application_notes